

[NAME OF DOCUMENT] Abstract

A contact pin (50) for contacting a terminal of a wafer and supplying a signal to that wafer is provided with a first conductive layer (51b) composed of a first conductive material having a relatively higher hardness than the oxide film formed on the terminal of the wafer, a second conductive layer (51c) composed of a second conductive material having a relatively lower hardness than the oxide film, and a base material (51a) with the first conductive layer (51b) and second conductive layer (51c) formed at the outside, the first conductive layer (51b) being formed so as to closely contact the outside of the second conductive layer (51c), the first conductive layer (51b) and second conductive layer (51c) both being exposed at the front end face (50a) of the contact pin (50).

5